

# HSM2836C

## Silicon Epitaxial Planar Diode for High Speed Switching

REJ03G0554-0400  
(Previous: ADE-208-030C)  
Rev.4.00  
Mar 10, 2005

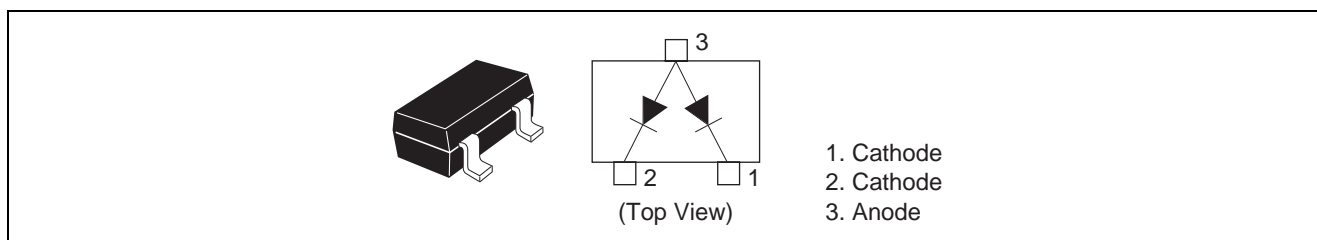
### Features

- Fast recovery time.
- MPAK package is suitable for high density surface mounting and high speed assembly.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSM2836C	A4	MPAK	PLSP0003ZC-A (MPAK)

### Pin Arrangement



**Absolute Maximum Ratings** \*<sup>1</sup>

(Ta = 25°C)

Item	Symbol	Value	Unit
Peak reverse voltage	$V_{RM}$	85	V
Reverse voltage	$V_R$	80	V
Peak forward current	$I_{FM}$	300	mA
Non-Repetitive peak forward surge current	$I_{FSM}$ * <sup>2</sup>	4	A
Average rectified current	$I_O$	100	mA
Junction temperature	$T_J$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

Notes: 1. Per one device.

2. Within 1  $\mu$ s forward surge current.**Electrical Characteristics** \*<sup>1</sup>

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_{F1}$	—	0.72	1.0	V	$I_F = 10$ mA
	$V_{F2}$	—	0.83	1.0		$I_F = 50$ mA
	$V_{F3}$	—	0.90	1.2		$I_F = 100$ mA
Reverse current	$I_R$	—	—	0.1	$\mu$ A	$V_R = 80$ V
Capacitance	C	—	2.5	4.0	pF	$V_R = 0$ V, $f = 1$ MHz
Reverse recovery time	$t_{rr}$	—	—	20	ns	$I_F = 10$ mA, $V_R = 6$ V, $R_L = 50$ $\Omega$

Note: 1. Per one device.

## Main Characteristic

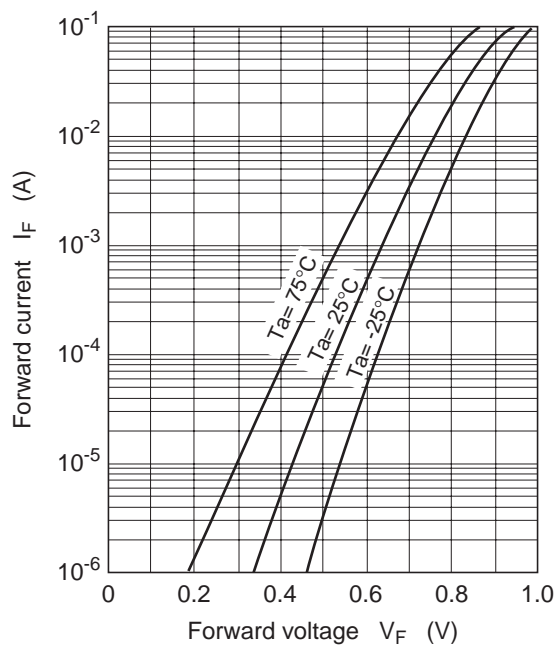


Fig.1 Forward current vs. Forward voltage

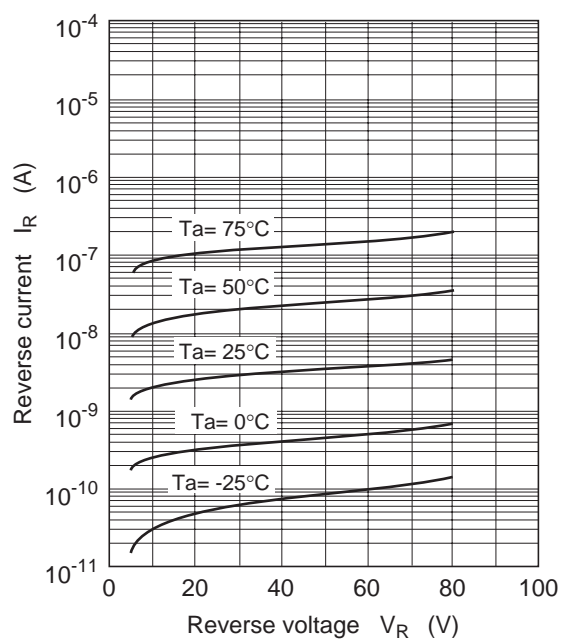


Fig.2 Reverse current vs. Reverse voltage

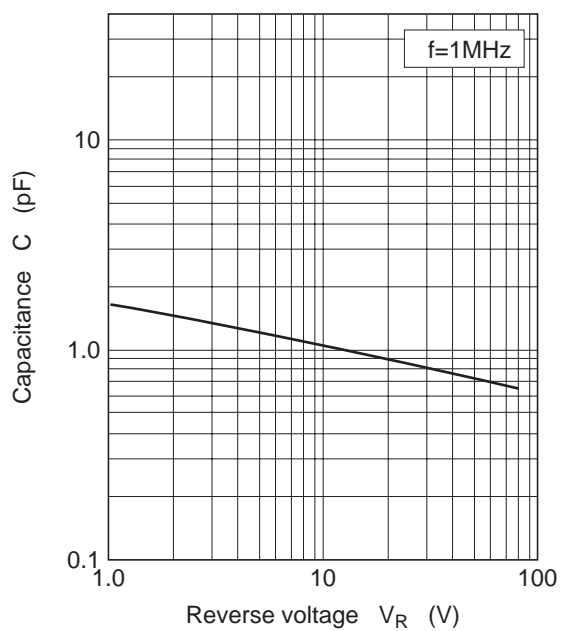
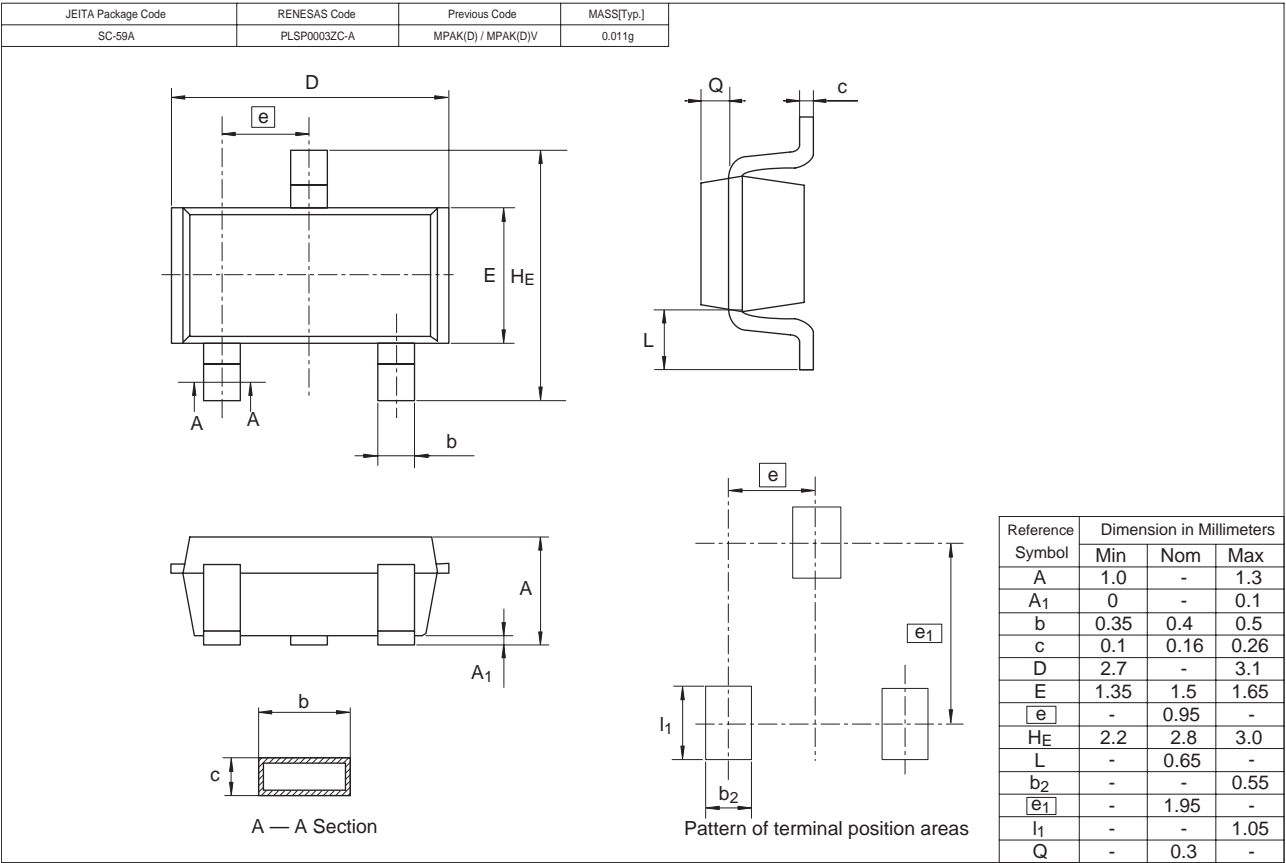


Fig.3 Capacitance vs. Reverse voltage

Package Dimensions



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